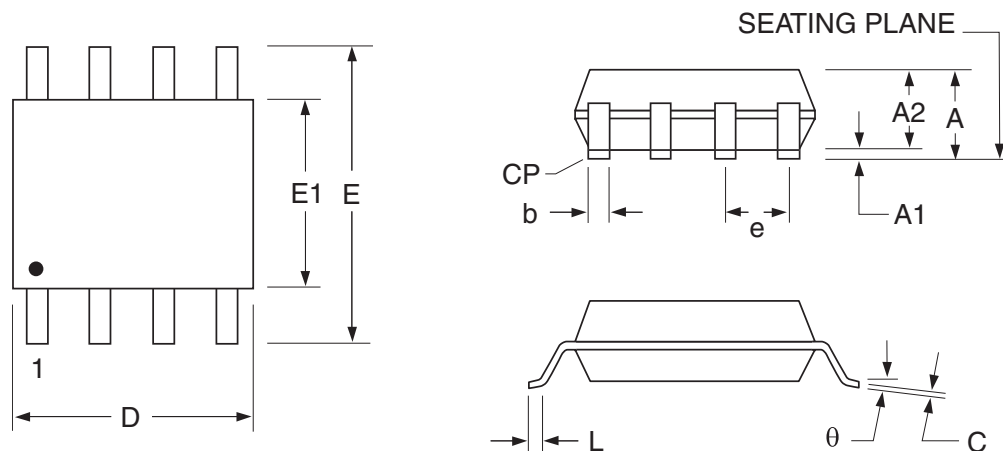


8-Pin SOIC 150-mil (Package Code N)



Package Dimensions⁽¹⁾

Symbol	Millimeters			Inches		
	Min	Typ.	Max	Min	Typ.	Max
A	1.47	1.60	1.72	0.058	0.063	0.068
A1	0.10		0.24	0.004		0.009
A2		1.45			0.057	
b	0.33	0.41	0.50	0.013	0.016	0.020
C	0.19	0.20	0.25	0.0075	0.008	0.0098
D ⁽³⁾	4.80	4.85	4.95	0.189	0.191	0.195
E	5.80	6.00	6.19	0.228	0.236	0.244
E1 ⁽³⁾	3.80	3.90	4.00	0.150	0.154	0.157
e ⁽²⁾	1.27 BSC			0.050 BSC		
L	0.40	0.71	1.27	0.015	0.028	0.050
theta	0°		8°	0°		8°
CP			0.10			0.004

Notes:

1. Controlling dimensions: inches, unless otherwise specified.
2. BSC = Basic lead spacing between centers.
3. Dimensions D and E1 do not include mold flash protrusions and should be measured from the bottom of the package.
4. Formed leads shall be planar with respect to one another within .0004 inches at the seating plane.